

MMBT2222LT1, MMBT2222ALT1

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector - Emitter Breakdown Voltage (I _C = 10 mAdc, I _B = 0) MMBT2222A	MMBT2222	V _{(BR)CEO}	30 40	- -	Vdc
Collector - Base Breakdown Voltage (I _C = 10 µAdc, I _E = 0) MMBT2222A	MMBT2222	V _{(BR)CBO}	60 75	- -	Vdc
Emitter - Base Breakdown Voltage (I _E = 10 µAdc, I _C = 0) MMBT2222A	MMBT2222	V _{(BR)EBO}	5.0 6.0	- -	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, V _{EB(off)} = 3.0 Vdc)	MMBT2222A	I _{CEX}	-	10	nAdc
Collector Cutoff Current (V _{CB} = 50 Vdc, I _E = 0) (V _{CB} = 60 Vdc, I _E = 0) (V _{CB} = 50 Vdc, I _E = 0, T _A = 125°C) (V _{CB} = 60 Vdc, I _E = 0, T _A = 125°C)	MMBT2222 MMBT2222A MMBT2222 MMBT2222A	I _{CBO}	- - - -	0.01 0.01 10 10	µAdc
Emitter Cutoff Current (V _{EB} = 3.0 Vdc, I _C = 0)	MMBT2222A	I _{EBO}	-	100	nAdc
Base Cutoff Current (V _{CE} = 60 Vdc, V _{EB(off)} = 3.0 Vdc)	MMBT2222A	I _{BL}	-	20	nAdc

ON CHARACTERISTICS

DC Current Gain (I _C = 0.1 mAdc, V _{CE} = 10 Vdc) (I _C = 1.0 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc, T _A = -55°C) (I _C = 150 mAdc, V _{CE} = 10 Vdc) (Note 4) (I _C = 150 mAdc, V _{CE} = 1.0 Vdc) (Note 4) (I _C = 500 mAdc, V _{CE} = 10 Vdc) (Note 4)	MMBT2222A only MMBT2222 MMBT2222A	h _{FE}	35 50 75 35 100 50 30 40	- - - - 300 - - -	-
Collector - Emitter Saturation Voltage (Note 4) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT2222 MMBT2222A	V _{CE(sat)}	- -	0.4 0.3	Vdc
(I _C = 500 mAdc, I _B = 50 mAdc)	MMBT2222 MMBT2222A		- -	1.6 1.0	
Base - Emitter Saturation Voltage (Note 4) (I _C = 150 mAdc, I _B = 15 mAdc)	MMBT2222 MMBT2222A	V _{BE(sat)}	- 0.6	1.3 1.2	Vdc
(I _C = 500 mAdc, I _B = 50 mAdc)	MMBT2222 MMBT2222A		- -	2.6 2.0	

SMALL-SIGNAL CHARACTERISTICS

Current - Gain - Bandwidth Product (Note 5) (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	MMBT2222 MMBT2222A	f _T	250 300	- -	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)		C _{obo}	-	8.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc, I _C = 0, f = 1.0 MHz)	MMBT2222 MMBT2222A	C _{ibo}	- -	30 25	pF
Input Impedance (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)	MMBT2222A MMBT2222A	h _{ie}	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)	MMBT2222A MMBT2222A	h _{re}	- -	8.0 4.0	X 10 ⁻⁴
Small - Signal Current Gain (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)	MMBT2222A MMBT2222A	h _{fe}	50 75	300 375	-
Output Admittance (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)	MMBT2222A MMBT2222A	h _{oe}	5.0 25	35 200	µmhos

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Characteristic	Symbol	Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS				
Collector Base Time Constant ($I_E = 20\text{ mAdc}$, $V_{CB} = 20\text{ Vdc}$, $f = 31.8\text{ MHz}$)	r_b, C_c	-	150	ps
Noise Figure ($I_C = 100\text{ }\mu\text{Adc}$, $V_{CE} = 10\text{ Vdc}$, $R_S = 1.0\text{ k}\Omega$, $f = 1.0\text{ kHz}$)	NF	-	4.0	dB

SWITCHING CHARACTERISTICS (MMBT2222A only)

Delay Time	$(V_{CC} = 30\text{ Vdc}$, $V_{BE(\text{off})} = -0.5\text{ Vdc}$, $I_C = 150\text{ mAdc}$, $I_{B1} = 15\text{ mAdc}$)	t_d	-	10	ns
Rise Time		t_r	-	25	
Storage Time	$(V_{CC} = 30\text{ Vdc}$, $I_C = 150\text{ mAdc}$, $I_{B1} = I_{B2} = 15\text{ mAdc}$)	t_s	-	225	ns
Fall Time		t_f	-	60	

4. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

5. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

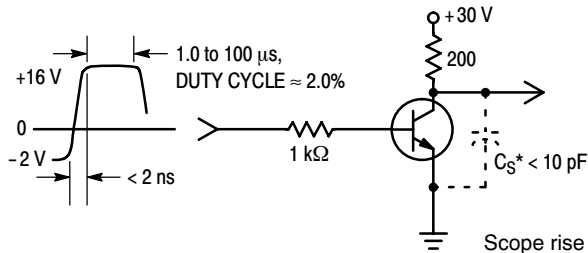


Figure 1. Turn-On Time

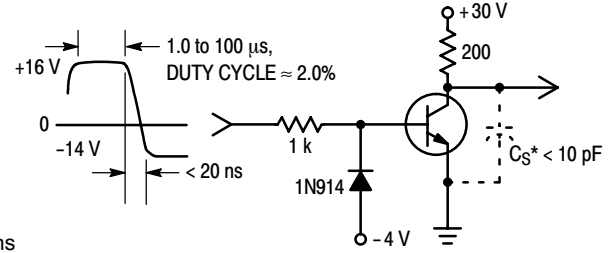


Figure 2. Turn-Off Time

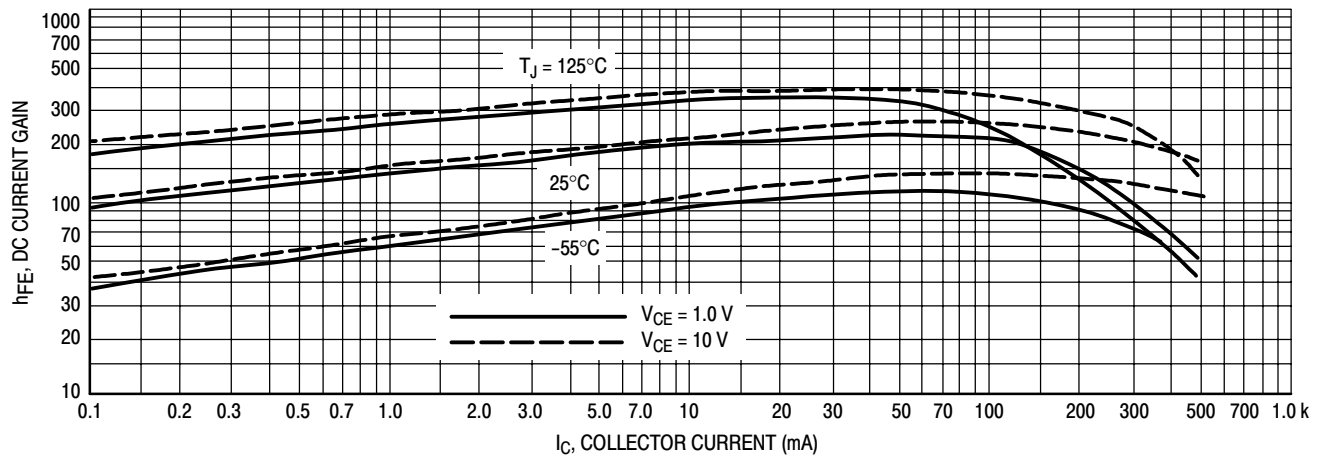


Figure 3. DC Current Gain

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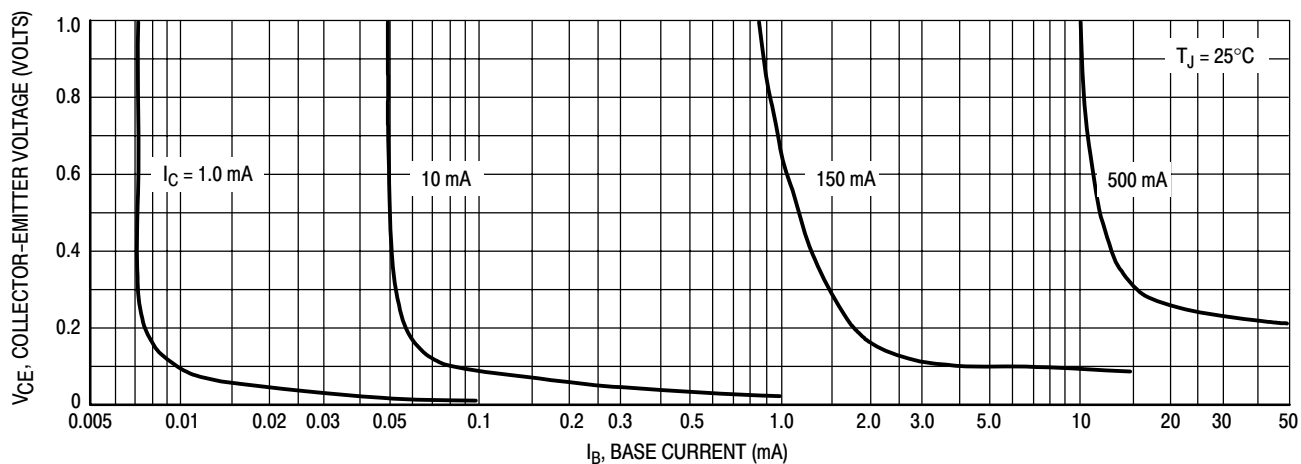


Figure 4. Collector Saturation Region

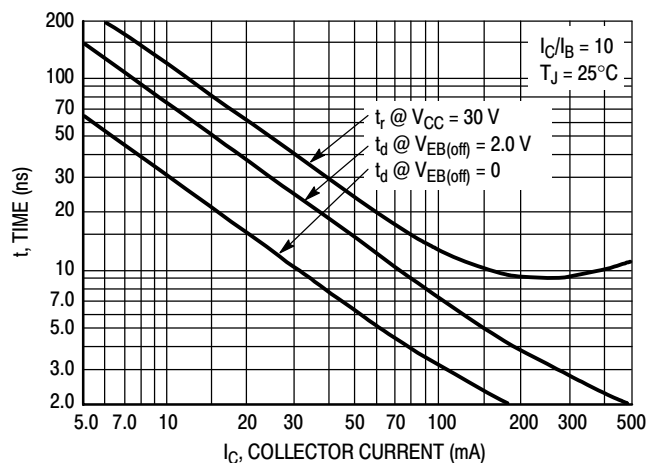


Figure 5. Turn-On Time

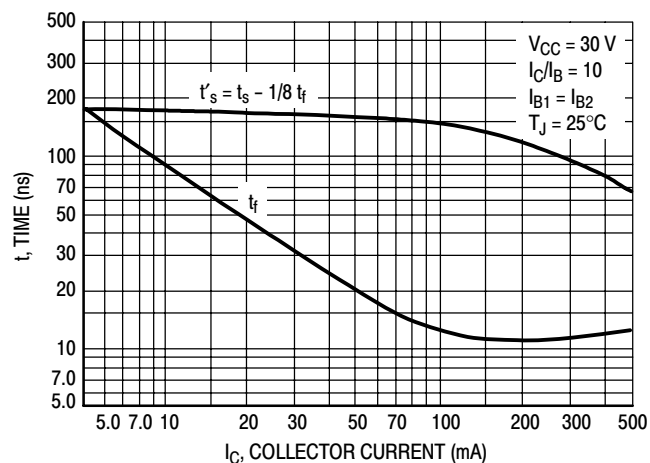


Figure 6. Turn-Off Time

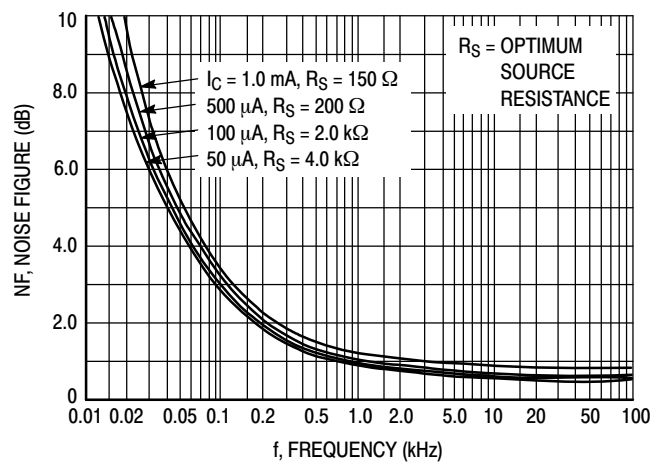


Figure 7. Frequency Effects

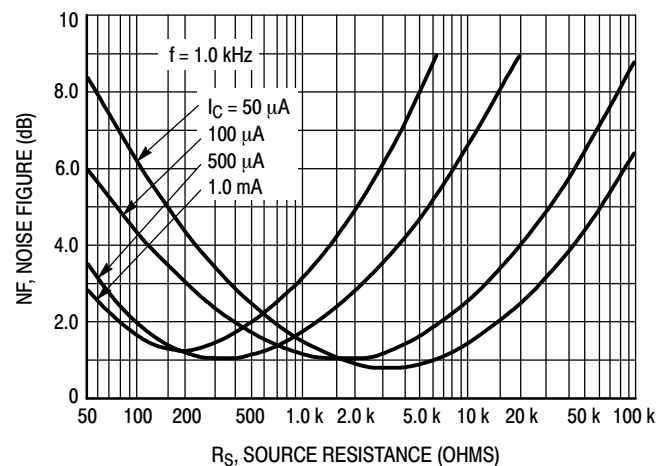


Figure 8. Source Resistance Effects

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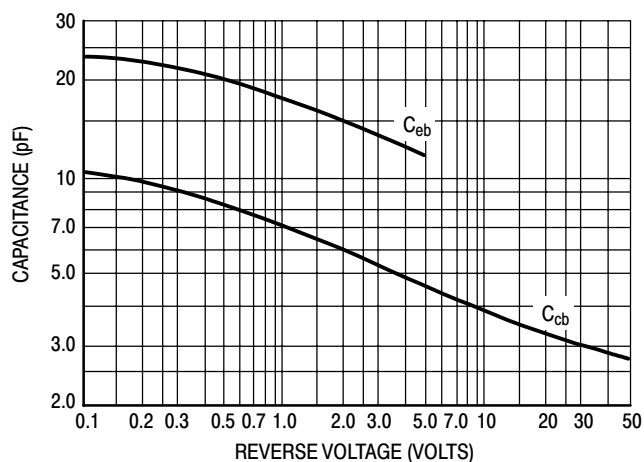


Figure 9. Capacitances

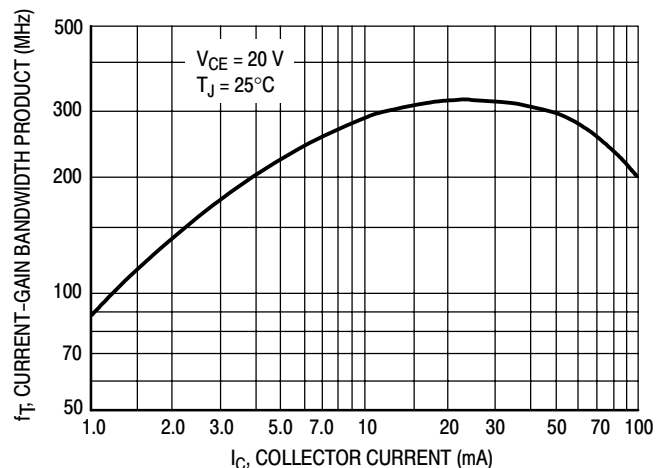


Figure 10. Current-Gain Bandwidth Product

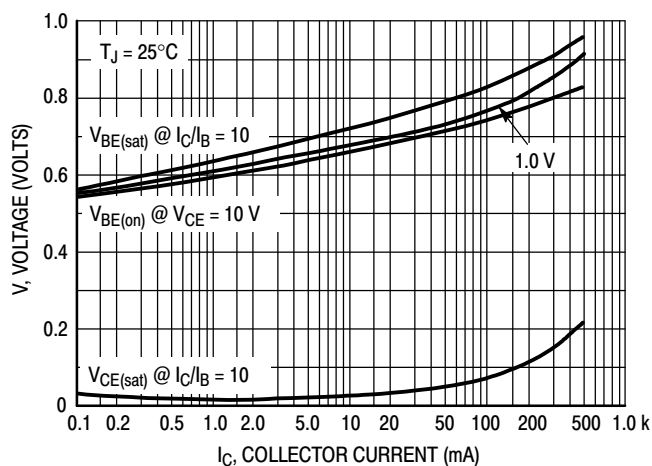


Figure 11. "On" Voltages

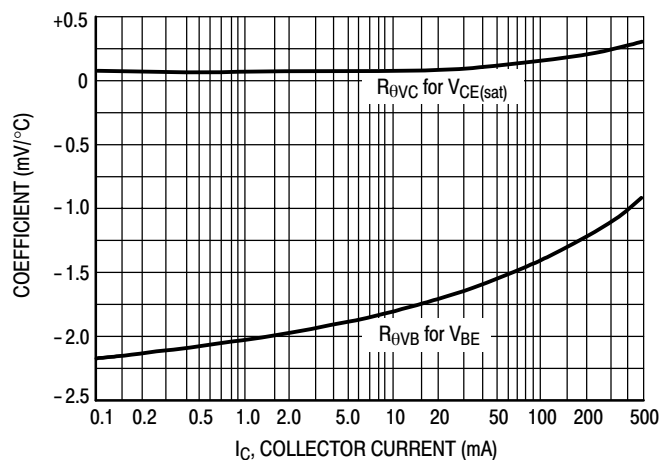


Figure 12. Temperature Coefficients

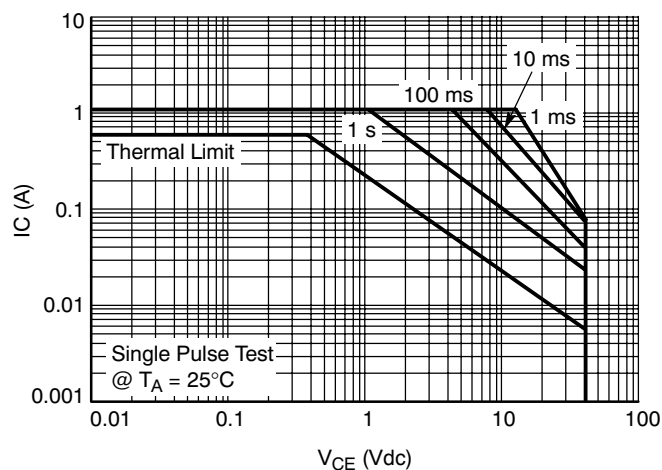


Figure 13. Safe Operating Area

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ORDERING INFORMATION

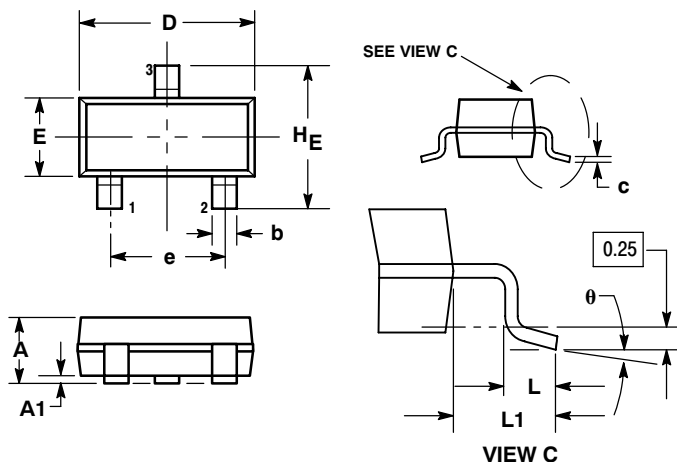
Device	Specific Marking Code	Package	Shipping†
MMBT2222LT1	M1B	SOT-23	3000 / Tape & Reel
MMBT2222LT1G	M1B	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222ALT1	1P	SOT-23	3000 / Tape & Reel
MMBT2222ALT1G	1P	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT2222LT3	M1B	SOT-23	10,000 / Tape & Reel
MMBT2222LT3G	M1B	SOT-23 (Pb-Free)	10,000 / Tape & Reel
MMBT2222ALT3	1P	SOT-23	10,000 / Tape & Reel
MMBT2222ALT3G	1P	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AN



NOTES:

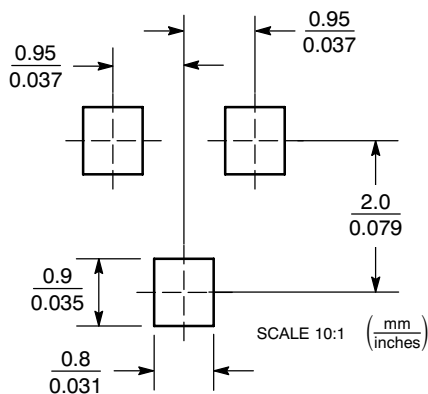
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104


STYLE 6:

- PIN 1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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